

# PATENT ASSIGNMENT

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| <b>SUBMISSION TYPE:</b>  | NEW ASSIGNMENT                 |
| <b>NATURE OF CONVEYANCE:</b>   | ASSIGNMENT                     |
| <b>CONVEYING PARTY DATA</b>  |                                |
| <b>Name</b>  | <b>Execution Date</b>          |
| Young-Ja KIM   | 06/08/2011                     |
| Junyoung KO  | 06/08/2011                     |
| <b>RECEIVING PARTY DATA</b>  |                                |
| <b>Name:</b>   | Samsung Electronics Co., Ltd.  |
| <b>Street Address:</b>   | 416, Maetan-dong, Yeongtong-gu |
| <b>City:</b>   | Suwon-si, Gyeonggi-do          |
| <b>State/Country:</b>  | REPUBLIC OF KOREA              |
| <b>PROPERTY NUMBERS Total: 1</b>   |                                |
| <b>Property Type</b>   | <b>Number</b>                  |
| <b>Application Number:</b>   | 13177167                       |
| <b>CORRESPONDENCE DATA</b>   |                                |
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| <b>ATTORNEY DOCKET NUMBER:</b>   | 239/336                        |
| <b>NAME OF SUBMITTER:</b>  | Eugene M. Lee                  |
| <b>Total Attachments: 1</b><br>source=Assignment_as_filed_2011_07_06#page1.tif       |                                |

OP \$40.00 13177167

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**PATENT**  
**REEL: 026549 FRAME: 0876**

**ASSIGNMENT**

|                              |   |
|------------------------------|---|
| Name and Address of Assignee | For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto<br><b>SAMSUNG ELECTRONICS CO., LTD.,</b><br><b>416, Maetan-dong, Yeongtong-gu</b><br><b>Suwon-si, Gyeonggi-do, Republic of Korea</b> |
|                              | (hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to   |

|                    |  |
|--------------------|--|
| Title of Invention | <b>WAFER DICING BLADE AND WAFER DICING APPARATUS INCLUDING THE SAME</b><br>as set forth in this United States Patent Application |
|--------------------|--|

|           |   |
|-----------|---|
| Check One | <input checked="" type="checkbox"/> executed concurrently herewith<br><input type="checkbox"/> executed on _____<br><input type="checkbox"/> Serial No. _____ Filed _____ |
|-----------|---|

in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefore or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of **LEE & MORSE, P.C.** the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

| <b>NAMES AND SIGNATURES OF INVENTORS</b> |                                |                         |
|--|--------------------------------|-------------------------|
| Name: <b>Young-Ja KIM</b>                | Signature: <i>Young-Ja Kim</i> | Date: <i>06/08 2011</i> |
| Name: <b>Junyoung KO</b>                 | Signature: <i>Junyoung Ko</i>  | Date: <i>6/8 2011</i>   |
| <b>NAMES AND SIGNATURES OF WITNESSES</b> |                                |                         |
| Name:                                    | Signature:                     | Date:                   |
| Name:                                    | Signature:                     | Date:                   |

Note: *Prima facie* evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from a U.S. Consul.